AUGUST 3-7
EMC+SIPI 2026
DALLAS, TEXAS

2026 IEEE INTERNATIONAL SYMPOSIUM ON ELECTROMAGNETIC COMPATIBILITY, SIGNAL & POWER INTEGRITY

RETURNING TO THE IEEE EMC+SIPI 2026 SYMPOSIUM IN DALLAS, TEXAS!

3RD GLOBAL SIGNAL INTEGRITY AND POWER INTEGRITY (SIPI) UNIVERSITY

TUESDAY-THURSDAY, AUGUST 4-6, 2026

Similar to the Clayton R. Paul Global EMC University that is held annually during the International Symposium, the intent is to offer two full days of lectures (Tuesday afternoon, all day Wednesday, and Thursday morning) carefully curated to cover basic and advanced concepts of SI & PI during the symposium week. SI & PI are gaining ever-growing attention due to the higher data rates and larger currents in modern high-speed digital systems. Industry requires skilled engineers with a background in these two disciplines to address the increasing complexity and challenges of electronic system design.

The IEEE EMC Society therefore decided to offer again – after the first two successful editions at the Symposium in Phoenix, Arizona (2024) and Raleigh, North Carolina (2025) – two full days of courses during the EMC+SIPI Symposium 2026 to bridge this gap. The mission of the Global SIPI University will be to give students, technicians, and engineers the opportunity to acquire SI & PI skills directly from experienced and well-known instructors from both industry and academia.

The program offers both lectures and practical demonstrations. The intent is to expand the discussion on the background concepts and to provide a more detailed presentation of advanced methods for addressing the current design challenges. Moreover, the demos will encompass the use of instruments typically employed for analysis, measurement and troubleshooting for signal and power integrity.

CO-CHAIR: Francesco de Paulis

Univ. L'Aquila, L'Aquila, Italy

Francesco de Paulis (Senior Member IEEE) received the M.S. degree in Electrical Engineering in May 2008 from Missouri University of Science and Technology (formerly University of Missouri-Rolla), USA, and the Ph.D. degree in Electrical and Information Engineering in 2012 from the University of L'Aquila, L'Aquila, Italy. He is currently an Associate Professor at the Electromagnetic Compatibility and Signal Integrity Laboratory at the University of L'Aquila. His main research interests are in signal and power integrity, high speed channel design and optimization, composite materials for shielding and absorption, RF interference in mixed-signal system, TSVs in silicon chips and interposers, antenna design and measurement techniques, remote fault detection in transmission lines, microwave design of electronic devices and systems for space applications.

CO-CHAIR: Majid Ahadi Dolatsara

Keysight Technologies

Dr. Majid Ahadi Dolatsara received his B.Sc. degree in electrical engineering from the K.N.Toosi University of Technology, Tehran, Iran, in 2013, and his M.Sc. degree in electrical engineering from the Colorado State University, Fort Collins, CO, USA, in 2016. He received his Ph.D. degree in electrical and computer engineering with a minor in computer science from the Georgia Institute of Technology, Atlanta, GA, USA in 2021, where he focused on development of machine learning based electronic design automation (EDA) tools for signal integrity and high-speed channels.

He has been with Keysight Technologies, Calabasas, CA, USA, since 2021, where he currently works as a senior machine learning R&D engineer developing ML-based modeling and optimization tools for EDA.

Please view the presentation abstracts and instructor bios available on the Symposium website: 2026.emcsipi.org/global-sipi-university

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TUESDAY (AFTERNOON) 1:00PM – 5:00PM AUGUST 4, 2026

TIME	TOPIC	PRESENTER/INSTRUCTOR
1:00pm – 1:30pm	**Registration / Introduction**	
1:30pm – 2:15pm	**Opening Session:** Overview of High-Speed Signal Integrity (SI)	Bhyrav Mutnury (AMD)
2:15pm – 3:00pm	**Introduction to SI and PI:** Evolution from the Basics to the Current Technology	Francesco de Paulis (Univ. L'Aquila)
3:00pm – 3:30pm	**Coffee Break / Networking**	
3:30pm – 4:15pm	**Signal Integrity I:** Transmission Line Effects, Lumped Effects, Passive Interconnect Design, Terminations and Reflections	John Golding (Siemens)
4:15pm – 5:00pm	**Signal Integrity II:** How Interconnects Work: The Physics of Losses, Reflections, and Coupling	Yuri Shlepnev (Simberian)

WEDNESDAY (FULL DAY) 8:00AM – 5:00PM AUGUST 5, 2026

TIME	TOPIC	PRESENTER/INSTRUCTOR
8:30am – 9:15am	**Signal Integrity III:** S-params In the Eyes of the Beholder: Interconnect Design Considerations at 224 Gb/s and 448 Gb/s	Brandon Gore (Samtec)
9:15am – 10:00am	**Signal Integrity IV:** Measurements for Signal Integrity (VNA and TDR)	Matteo Cocchini (IBM)
10:00am – 10:30am	**Coffee Break / Networking**	
10:30am – 11:15am	**Keynote:** Powering AI Performance from Silicon to System: The Role of SIPI	Barry Katz (Mathworks)
11:15am – 12:00pm	**Signal Integrity Demo I:** Time Domain – Scope Measurements of the Impact of Transmission Line Effects and Reflections Demonstrating Ringing Noise, Time of Flight and Eye Diagrams	Eric Bogatin (Univ. Colorado)
12:00pm – 1:30pm	**Lunch Break / Networking**	
1:30pm – 2:15pm	**Signal Integrity V:** Simulation and Modeling of Signal Integrity for High-Speed Wired Communications	Renato Rimolo Donadio (TEC Costarica)
2:15pm – 3:00pm	**Signal Integrity Demo I:** Frequency Domain - VNA (Calibration and Channel Analysis)	Paul Peterson (R&S)
3:00pm – 3:30pm	**Coffee Break / Networking**	
3:30pm – 4:15pm	**Signal Integrity VI:** Unmasking The DUT: Fixture De-Embedding Essentials	Giorgi Maghlakelidze (Nvidia)
4:15pm – 5:00pm	**Power Integrity I:** Power Integrity Fundamentals	Dan Chirpich (Re:Build AppliedLogix)

THURSDAY (MORNING) 8:00AM – 12:00PM AUGUST 6, 2026

TIME	TOPIC	PRESENTER/INSTRUCTOR
8:30am – 9:15am	**Power Integrity II:** VRM Basics, VRM Modeling, and IR Drop	Chulsoon Hwang (MS&T)
9:15am – 10:00am	**Power Integrity III:** Package and IC PDN, On-Chip VRM	Michael Hill (Intel)
10:00am – 10:30am	**Coffee Break / Networking**	
10:30am – 11:15am	**Power Integrity Demo I:** Low Impedance PDN Measurements	Benjamin Dannan (Signal Edge Solutions)
11:15am – 12:00pm	**Closing Session:** Understanding Vias for Better SI and PI – 50+ Years of Physics-Based Modeling	Christian Schuster (TUHH)